

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	10087	(semiconductor or chip or die or IC) with (interposer or interconnect\$3 or redistribut\$3) with between	USPAT	OR	ON	2005/03/16 20:39
L2	611	1 and 257/777	USPAT	OR	ON	2005/03/16 20:12
L3	3572	(semiconductor or chip or die or IC) with (interposer or (interconnect\$3 or redistribut\$3) with (layer or film)) with between	USPAT	OR	ON	2005/03/16 20:39
L4	1495	(semiconductor or chip or die or IC) with (interposer or (interconnect\$3 or redistribut\$3) near (layer or film)) with between	USPAT	OR	ON	2005/03/16 22:24
L5	2723	257/777	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 22:34
L6	2656	257/692	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 22:34